

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1178	257/783.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:32
L2	2421	257/787.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:32
L3	158	257/783.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/28 11:33
L4	1791	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/28 11:33
L5	168	438/959.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:33
L6	1977	438/118.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:33
L7	1922	438/127.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:33
L8	85	L1 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:37

L9	124	L2 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:37
L10	4	L5 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:37

L11	5	L5 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:38
L12	138	L6 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:38
L13	146	L7 and (chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:38

L14	1	((chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/28 11:38
L15	0	((chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish or damage) and thick and (rigid or hard or metal) and (ball or bump or terminal)). clm.	US-PGPUB	OR	ON	2008/08/28 11:39

L16	974	(chip or die or element) and (plate or board or sheet) and (resin or adhesive or encapsula\$2) and (side or peripher\$2 or edge) and (polish or finish) and (damage or defect) and thick and (rigid or hard) and (ball or bump or terminal) and (shape or size) and (deform or warp)	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:53
L17	691	L16 and (large or high) and micro\$2	US-PGPUB; USPAT; USOCR	OR	ON	2008/08/28 11:58
L18	51	257/E23.133. ccls.	EPO; JPO	OR	ON	2008/08/28 12:42

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